



N-Channel 30-V (D-S) Fast Switching MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A)		
30	0.0075 at V _{GS} = 10 V	17.8		
	$0.0082 \text{ at V}_{GS} = 4.5 \text{ V}$	17.0		

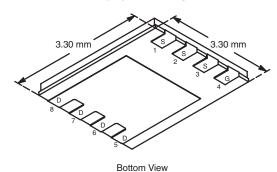
FEATURES

- TrenchFET[®] Power MOSFET
- New Low Thermal Resistance PowerPAK® Package with Low 1.07 mm Profile



- 100 % R_a Tested
- Lead (Pb)-free Version is RoHS Compliant

PowerPAK 1212-8

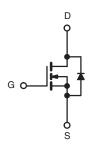


Ordering Information: Si7112DN-T1

Si7112DN-T1-E3 (Lead (Pb)-free)

APPLICATIONS

· Synchronous Rectification



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted					
Parameter		Symbol	10 sec	Steady State	Unit
Drain-Source Voltage		V _{DS}	30		V
Gate-Source Voltage		V _{GS}	± 12		
Continuous Drain Current /T 150 °C\a	T _A = 25 °C	I _D	17.8	11.3	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		14.2	9.1	
Pulsed Drain Current		I _{DM}	60		Α
Continuous Source Current (Diode Conduction) ^a		I _S	3.2	1.3	
Single Avalanche Current	L = 0.1 mH	I _{AS}	20		
Single Avalanche Energy	L=0.11IIII	E _{AS} 20		mJ	
Mariana Barra Birata di ad	T _A = 25 °C	I D	3.8	1.5	W
Maximum Power Dissipation ^a	T _A = 70 °C		2.0	0.8	VV
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C
Soldering Recommendations (Peak Temperature) ^{b, c}			260		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manipania Ingation to Applicati	t ≤ 10 sec	- R _{thJA}	24	33	°C/W
Maximum Junction-to-Ambient ^a	Steady State		65	81	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.9	2.4	

a. Surface Mounted on 1" x 1" FR4 Board.
b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

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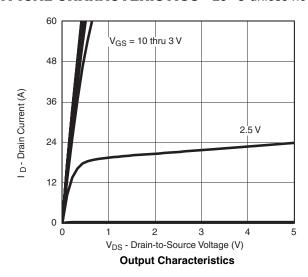
MOSFET SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.6		1.5	٧	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 12 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α	
	r	V _{GS} = 10 V, I _D = 17.8 A		0.006	0.0075		
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 4.5 V, I _D = 17 A		0.0065	0.0082	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 17.8 A		97		S	
Diode Forward Voltage ^a	V_{SD}	$I_S = 3.2 \text{ A}, V_{GS} = 0 \text{ V}$		0.7	1.2	V	
Dynamic ^b							
Input Capacitance	C _{iss}			260		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		340			
Reverse Transfer Capacitance	C _{rss}			145			
Total Gate Charge	Q_g			18	27	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 17.8 \text{ A}$		6.2			
Gate-Drain Charge	Q_{gd}			3.1			
Gate Resistance	R_g	f = 1 MHz	0.5	1.2	1.8	Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		10	15	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 1 A, V_{GEN} = 10 V, R_g = 6 Ω		65	100		
Fall Time	t _f			10	15		
Body Diode Reverse Recovery Time	t _{rr}	I _F = 3.2 A, di/dt = 100 A/μs		30	60		
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = 3.2 \text{ A}$, $U/UI = 100 \text{ A}/\mu\text{S}$		18		nC	

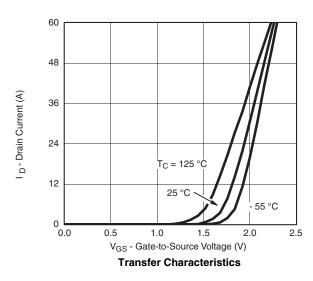
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C unless noted



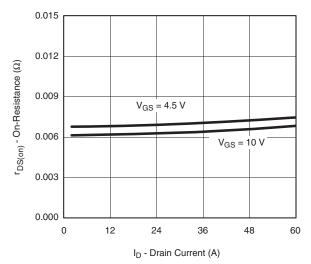




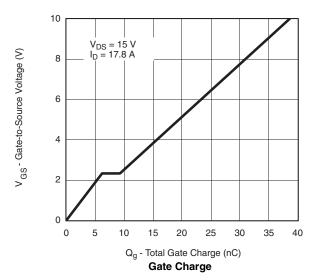


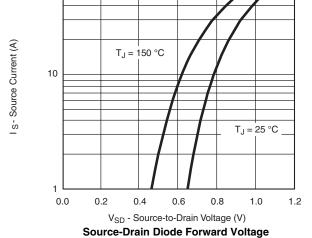


TYPICAL CHARACTERISTICS 25 °C unless noted



On-Resistance vs. Drain Current

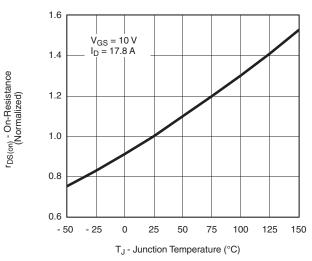




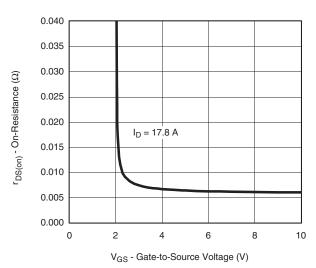
3500 3000 C_{iss} 2500 C - Capacitance (pF) 2000 1500 1000 500 0 5 10 0 15 20 25 30

V_{DS} - Drain-to-Source Voltage (V)

Capacitance



On-Resistance vs. Junction Temperature



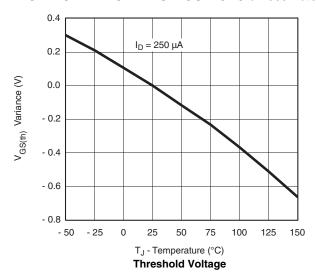
On-Resistance vs. Gate-to-Source Voltage

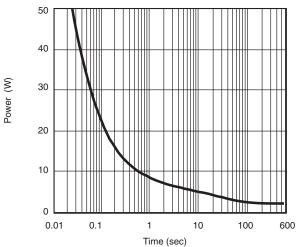
60

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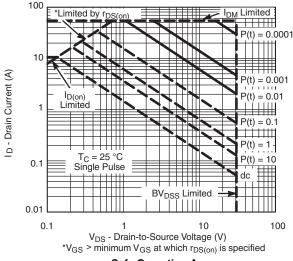
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TYPICAL CHARACTERISTICS 25 °C unless noted

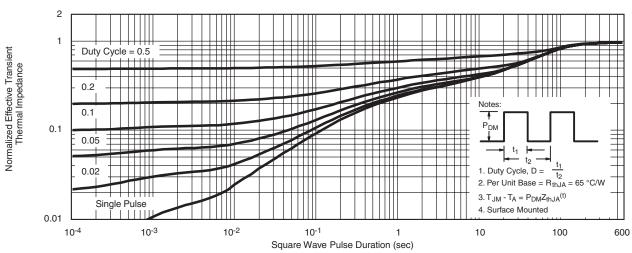




Single Pulse Power, Junction-to-Ambient





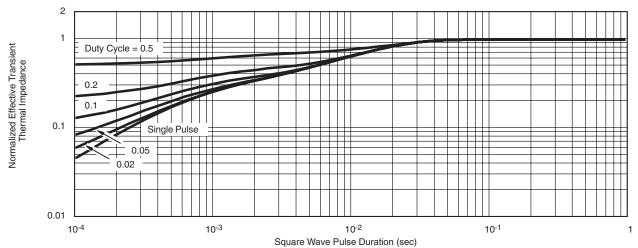


Normalized Thermal Transient Impedance, Junction-to-Ambient





TYPICAL CHARACTERISTICS 25 °C unless noted



Normalized Thermal Transient Impedance, Junction-to-Case

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